PCN Number:		20200218000.2A					PCN	CN Date: April 7, 2020		April 7, 2020
Title: Qualify TI Chengdu as an additional Assembly							r sel	ect c	levic	es
Custom	er Contact:	PCN Manager Dept				Quality Services				
Proposed 1 st Ship Da		te: Aug 18, 2020			20	Estimated Sample Availability:		P	rovided upon Request	
Change Type:										
Assembly Site					Design				Wafer Bump Site	
Assembly Process					Data Sheet				Wafer Bump Material	
Assembly Materials					Part num			Wafer Bump Process		
Mechanical Specification				Test Site				Wafer Fab Site		
□ Packing/Shipping/Labeling				Test Process				Wafer Fab Materials		
·									Waf	er Fab Process
	·				PCN De	etails				

Description of Change:

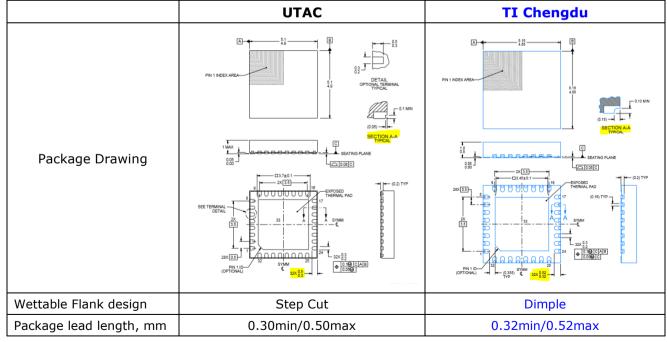
Revision A is to update the description of change to include a change on the Wettable flank design and package lead length for the affected devices. We apologize for any inconvenience this may have caused.

Texas Instruments is pleased to announce the qualification of TI Chengdu as additional Assembly Site for Select Devices listed in the "Product Affected" Section. Material differences are as follows.

Material Differences:

	UTAC	TI Chengdu
Mount compound	PZ0035	4207123
Leadframe finish	Matte Sn	NiPdAu

Package Outline Drawing Differences:



Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None **Anticipated impact on Material Declaration** Material Declarations or Product Content reports are driven from No Impact to the Material Declaration production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change. Changes to product identification resulting from this PCN: Assembly Site UTAC Thai Limited Assembly Site Origin (22L) ASO: NSE TI Chengdu Assembly Site Origin (22L) ASO: CDA Sample product shipping label (not actual product label) ECAT: G4 = NiPdAu ECAT: G3 = Matte (1P) SN74LS07NSR MADE IN: Malaysia 2DC: 20: (a) 2000 (D) 0336 31T)LOT: 3959047MLA 4W) TKY(1T) 7523483SI2 MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 P) 2P) REV: (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS LBL: 5A (L)TO:1750 **Product Affected** DRV8702DQRHBRQ1 DRV8702QRHBRQ1 DRV8703QRHBRQ1 DRV8703DQRHBRQ1 DRV8702DQRHBTQ1 DRV8702QRHBTQ1 DRV8703DQRHBTQ1 DRV8703QRHBTQ1

Qualification Report

Automotive New Product Qualification Summary (As per AEC-Q100 and JEDEC Guidelines) Approve Date 12-Feb-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Spec	Min Lot	SS/Lot	Test Name / Condition	Duration	Qual Device: DRV8702QRHBRQ1	Qual Device: DRV8703QRHBRQ1
	Test	Group A – A	Qty .cceler	ated Envi	ronment Stress T	ests		
PC	A1	-	3	22	SAM Analysis, Pre Stress	Completed	-	3/66/0
PC	A1	JEDEC J- STD-020 JESD22- A113	3	77	Preconditioning	Level 2- 260C	-	No fails
PC	A1	-	3	22	SAM Analysis, Post Stress	Completed	-	3/66/0
HAST	A2	JEDEC JESD22-	3	77	Biased HAST, 130C/85%RH	96 Hours	-	3/240/0

Туре	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: DRV8702QRHBRQ1	Qual Device: DRV8703QRHBRQ1
HAST	A2	A110 -	3	1	Cross Section, Post bHAST 96 Hours	Completed	-	3/3/0
HAST	A2	-	3	30	Wire Bond Shear, Post bHast, 96 Hours	Wires	-	3/90/0
HAST	A2	-	3	30	Bond Pull over Stitch, post bHAST, 96 Hours	Wires	-	3/90/0
HAST	A2	-	3	30	Bond Pull over Ball, Post bHAST, 96 Hours	Wires	-	3/90/0
HAST	A2	JEDEC JESD22- A110	3	70	Biased HAST, 130C/85%RH	192 Hours	-	3/210/0
HAST	A2	-	3	1	Cross Section, Post bHAST 192 Hours	Completed	-	3/3/0
HAST	A2	1	3	22	SAM Analysis, Post bHAST, 192 Hours	Completed	-	3/66/0
HAST	A2	-	3	30	Wire Bond Shear, Post bHast, 192 Hours	Wires	-	3/90/0
HAST	A2	-	3	30	Bond Pull over Stitch, post bHAST, 192 Hours	Wires	-	3/90/0
HAST	A2	-	3	30	Bond Pull over Ball, Post bHAST, 192 Hours	Wires	-	3/90/0
TC	A4	JEDEC JESD22- A104 and Appendix 3	3	77	Temperature Cycle, - 65/150C	500 Cycles	-	3/298/0
TC	A4	-	3	1	Cross Section, Post T/C 500 Cycles	Completed	-	3/3/0
TC	A4	-	3	22	SAM Analysis, Post T/C, 500 Cycles	Completed	-	3/66/0
тс	A4	-	3	30	Wire Bond Shear, Post T/C 500 Cycles	Wires	-	3/90/0
тс	A4	-	3	30	Bond Pull over Stitch Post T/C 500 Cycles	Wires	-	3/90/0
TC	A4	-	3	30	Bond Pull over Ball Post T/C 500 Cycles	Wires	-	3/90/0

Туре	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: DRV8702QRHBRQ1	Qual Device: DRV8703QRHBRQ1
TC	A4	JEDEC JESD22- A104 and Appendix 3	3	70	Temperature Cycle, - 65/150C	1000 Cycles		3/230/1*
тс	A4	1	3	1	Cross Section, Post T/C 1000 Cycles	Completed	1	3/3/0
TC	A4	1	3	22	SAM Analysis, Post T/C, 1000 Cycles	Completed	1	3/66/0
TC	A4	-	3	30	Wire Bond Shear, Post T/C 1000 Cycles	Wires	-	3/90/0
TC	A4	-	3	30	Bond Pull over Stitch, Post T/C, 1000 Cycles	Wires	-	3/90/0
тс	A4	-	3	30	Bond Pull over Ball, Post T/C, 1000 Cycles	Wires	-	3/90/0
PTC	A5	JEDEC JESD22- A105	1	45	Power Temperature Cycle -40/125C	1000 Cycles	-	-
PTC	A5	JEDEC JESD22- A105	1	45	Power Temperature Cycle -40/125C	2000 Cycles	-	-
HTSL	A6	JEDEC JESD22- A103	3	45	High Temp Storage Bake 150C	1000 Hours	-	3/138/0
HTSL	A6	-	3	1	Cross Section, Post HTSL 1000 Hours	Completed	-	3/3/0
HTSL	A6	JEDEC JESD22- A103	3	44	High Temp Storage Bake 150C	2000 Hours	-	3/135/0
HTSL	A6	-	3	1	Cross Section, Post HTSL 2000 Hours	Completed	-	3/3/0

A1 (PC): Preconditioning:

Performed for THB, Biased HAST, AC, uHAST & TC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C Grade 1 (or Q): -40C to +125C Grade 2 (or T): -40C to +105C Grade 3 (or I): -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold: HTOL, ED

Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room: AC/uHAST

*: 1 TC fail due to EOS not related to TC, 8D available.

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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